

The Leading International Components, Packaging, and Manufacturing Technology Symposium



15th IEEE CPMT Symposium Japan

November 10 – 12, 2026

Venue: Ritsumeikan University Suzaku Campus, Kyoto, JAPAN

(On-site only)

<https://www.ieee-csj.org>

“Challenge of Advanced Packaging for AI / Data center and its Utilization Technology”

“IEEE CPMT Symposium Japan (ICSJ)” is one of the most widely recognized international conferences sponsored by the **IEEE Electronics Packaging Society (EPS)** and is held annually in Kyoto every November. This conference was inaugurated in 1992 as “The VLSI Packaging Workshop in Japan (VPWJ)” to provide a platform to communicate and interact with global leaders in packaging technology. Later in 2010, this conference was renamed to “ICSJ,” and ICSJ2026 is the 15th ICSJ meeting, or 24th conference since establishing VPWJ.

Challenge of Advanced Packaging for AI / Data center and its Utilization Technology: The driving force behind semiconductor rapid growth is shifting to artificial intelligence (AI) and data centers are becoming essential for handling highly complex calculations and massive data processing. To realize AI / Data center, advanced packaging technology is essential to achieve ultra high-speed transmission, low latency, low power, high bandwidth, high power density and efficient cooling. On the other hand, AI and Deep learning (DL) can be utilized to realize rapid high-density and complex package structure design, electrical and thermal stress verification, material design, and process optimization. This cycle will further accelerate AI and packaging technology, making our lives more convenient. In 2026, our focus is on key electronics packaging technologies for AI / Data center and its utilization and emphasizes the following main topics: **Photonics, Advanced Packaging & Emerging Technologies, Process & Material, Power & Automotive Electronics, Signal/Power Integrity, and Bioelectronics & Healthcare.** Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

- + 2.xD & 3D package for chiplets and Si/Glass/Panel interposer
- + Fine pitch assembly & hybrid bonding
- + Materials & processing for interconnects and performance
- + Co-packaged Optics (CPO) & materials for optical packaging
- + Packaging for high-speed electronic interconnect
- + Packaging for neuromorphic or quantum computing
- + Packaging for sensor & MEMS devices
- + Signal integrity & power integrity
- + RF, mmWave, THz package & modules
- + Low power, low temperature & ultra-low noise system packaging
- + Machine learning, deep learning, modeling, AI-based multiphysics simulation



This conference will be a perfect opportunity to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an “Early Career Researchers’ (ECR)” session for young researchers with less than two year’s experience in their professions and all students including Ph.D. to hold fruitful discussions with the experts. The ECR sessions will be held as a poster session. Authors are invited to submit an abstract through our website <https://www.ieee-csj.org>. **The abstract deadline is May 29, 2026.** Notification of acceptance will be sent

by July 3, 2026, and the successful authors would then be requested to submit a 4-page manuscript by September 4, 2026, for the Technical Digest, which will be available via **IEEE Xplore Digital Library**, while the authors for the ECR session are required to submit a 2-page manuscript.

ICSJ2026 Steering Committee:

General Chair	Kazuyuki Nakagawa	(Renesas Electronics Corporation)
Vice Chair	Takafumi Fukushima	(Tohoku University)
	Kitty Pearsall	(Boss Precision Inc.)
Program Chair	Kenji Takahashi	(AIST)
	Kentaro Kaneko	(Ritsumeikan University)
	Motohito Takezaki	(Hakusan Inc.)
	Satomi Kawamoto	(Namics Corporation)
	Hideyuki Nawata	(Nissan Chemical Corporation)
Conference Relations Chair	Shinya Takyu	(LINTEC Corporation)
	Eiji Higurashi	(Tohoku University)
	Yutaka Uematsu	(Hitachi, Ltd.)
Promotion Chair	Takaaki Ishigure	(Keio University)
	Hideyuki Nasu	(Furukawa Electric Co., Ltd.)
	Taiji Sakai	(TSMC Japan 3DIC R&D Center, Inc.)
Financial Chair	Hidetoshi Numata	(IBM Research - Tokyo)
	Jun Maeda	(LINTEC Corporation)
	Kei Murayama	(Rapidus Corporation)
Publication/Web Chair	Junichi Inoue	(Kyoto Institute of Technology)
	Chinami Marushima	(IBM Japan, Ltd.)
	Nobuo Ohata	(Mitsubishi Electric Corporation)
Sponsor-Care Chair	Tadatomo Yamada	(LINTEC Corporation)
	Wataru Shiroi	(Renesas Electronics Corporation)
	Ryo Sakamaki	(AIST)
Arrangement Chair	Takashi Hare	(Toray Engineering Co., Ltd.)
	Kai Takeuchi	(Tohoku University)
	Kazutaka Maeda	(KYOCERA Corporation)
	Yuta Sugawara	(KYOCERA Corporation)
	Kentaro Kaneko	(Ritsumeikan University)

Financial Sponsor:

IEEE Electronics Packaging Society (EPS)

Technical Co-Sponsor:

IEEE EPS Japan Chapter



On-site Conference Venue:

Ritsumeikan University Suzaku Campus
Nishinokyosuzakucho 1, Nakagyoku, Kyoto, 604-8520

